

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5840373

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ROBERT CLARK	04/15/2019
KANDABARA TAPILY	10/30/2019
JEFFREY SMITH	11/26/2019
ANGELIQUE RALEY	11/12/2019
QIANG ZHAO	04/03/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TOKYO ELECTRON LIMITED
<b>Street Address:</b>	AKASAKA BIZ TOWER
<b>Internal Address:</b>	3-1 AKASAKA 5-CHOME, MINATO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	107-6325
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16356372
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	512.424.1000
<b>Email:</b>	TEHIPDocket@us.tel.com
<b>Correspondent Name:</b>	TOKYO ELECTRON U.S. HOLDINGS, INC.
<b>Address Line 1:</b>	2400 GROVE BLVD.
<b>Address Line 4:</b>	AUSTIN, TEXAS 78741
<b>ATTORNEY DOCKET NUMBER:</b>	180487US08
<b>NAME OF SUBMITTER:</b>	JORDAN GREGGERSEN
<b>SIGNATURE:</b>	/Jordan Greggersen/
<b>DATE SIGNED:</b>	11/26/2019
This document serves as an Oath/Declaration (37 CFR 1.63).	

**Total Attachments: 15**

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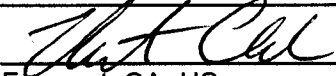
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Inventor's Signature:  Date: 4/15/2019  
Residence City/State/Country: Fremont, CA, US  
Mailing Address: 2859 Bayview Drive, Fremont, CA 94538, US  
Mailing Address: \_\_\_\_\_  
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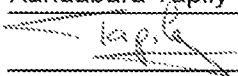
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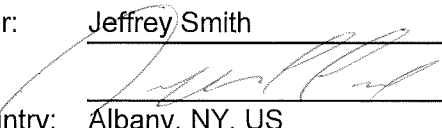
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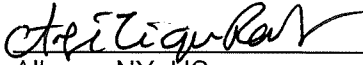
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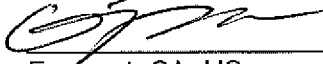
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(3) Legal name of Inventor: Jeffrey Smith  
 Inventor's Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
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